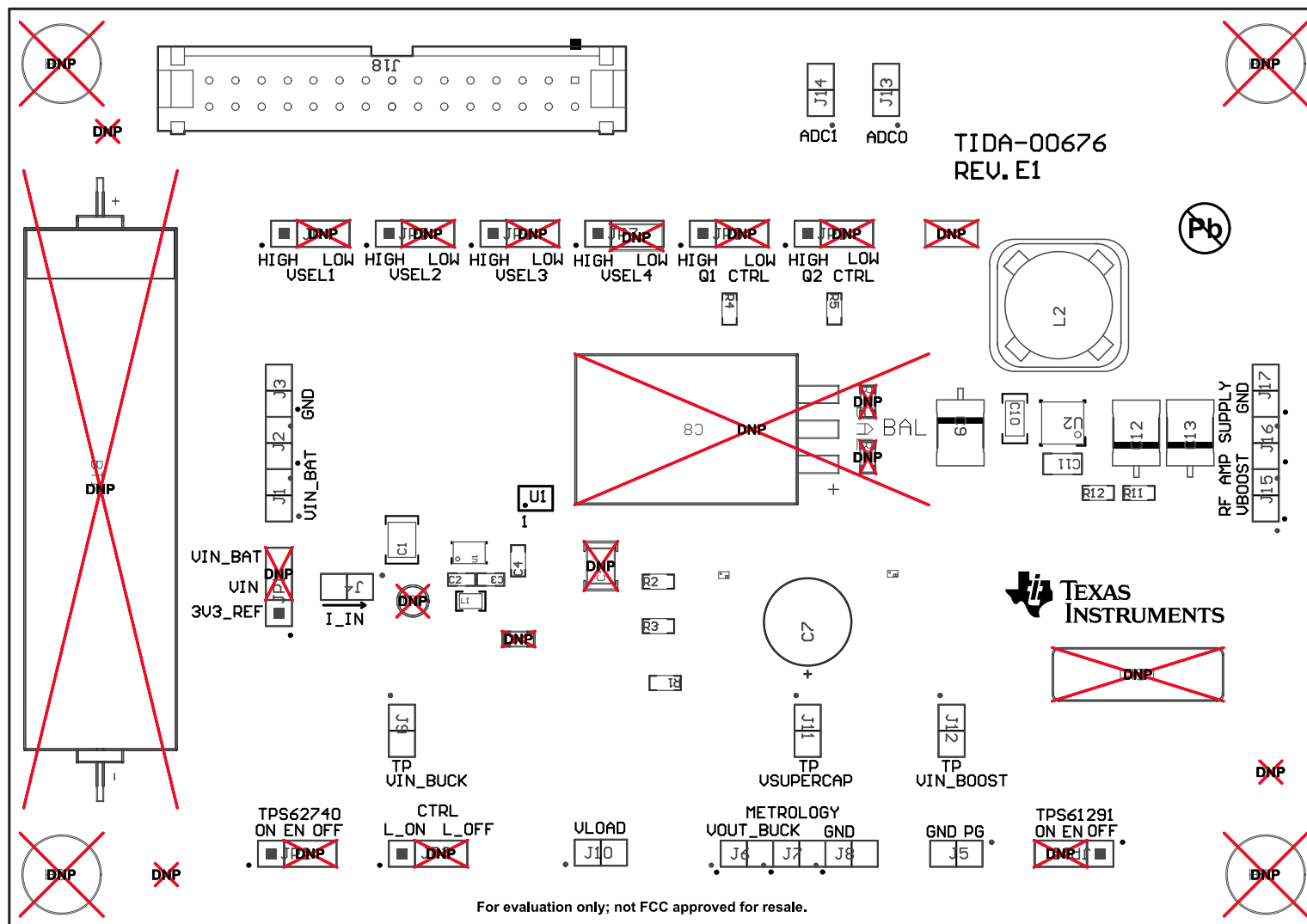


Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00676	REV: E1	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = TopAssembly Drawing	GENERATED : 04.09.2015 10:53:19	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00676	REV: E1	SVN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 04.09.2015 10:53:20	TEXAS INSTRUMENTS	

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